

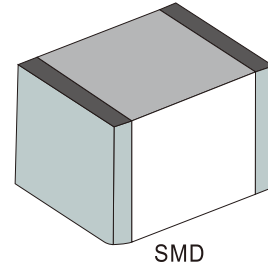
Type KW3S2R Series/ 貼片氣體放電管 Surface mounted Gas Discharge Tube

RoHS

Features

- Small Size Design EIA 1812 4.5X3.2X2.7mm
- Current Handling Capability 2KA @ 8/20us
- Low Capacitance and Insertion Loss
- Fast Response and Long Service Life
- Reliable to Protect Electrostatic Surge
- Moisture sensitivity level:Level 1

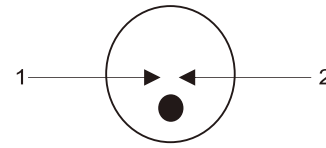
Exterior



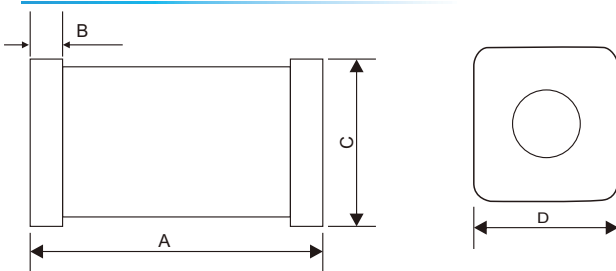
Agency Approvals

Icon	Description
ROHS	Compliance with 2011/65/EU
HF	Compliance with IEC61249-2-21:2003
	Mean Lead free
	Compliance with UL497B,Certificated E324754

Schematic Symbol

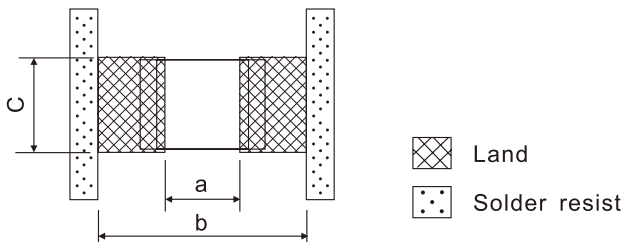


Dimensions(Unit:mm)



REF	min
A	4.5±0.3
B	0.5±0.2
C	2.7±0.3
D	3.2±0.3

Recommended Soldering Pad

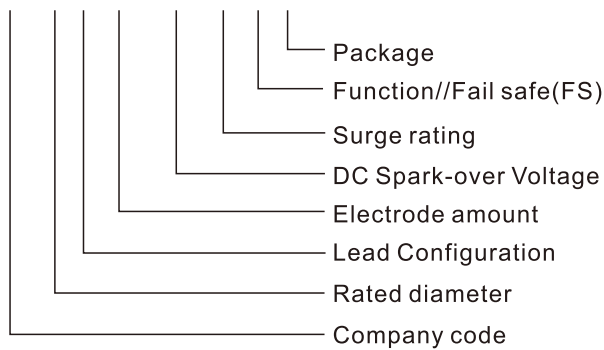


Soldering Moder	Dimensions(mm)		
	a	b	c
Reflow Soldering	2.7	6.5 to 8.5	3.4
Flow Soldering	2.9	6.5 to 9.5	3.6

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Part Numbering system

KW 3 S 2R XXX N O S



Electrical Specifications

Catalog Number 料號	DC Spark-Over Voltage 標稱直流擊穿電壓 100V/s Vs(V)	Impulse Spark-Over 衝擊擊穿電壓 1KV/μs Vis(V) Max.	Nom Impulse Discharge Current 耐衝擊電流 10x700μs kV	Nom Impulse Discharge Current 耐衝擊電流 8x20μs(kA)	Insulation Resistance 絕緣電阻		Capacitance 電容值 C 1kHz<6V pF Max.
					Min. MΩ	DC V	
KW3S2R75	75±30%	500	4.0	2.0	100	50	1.0
KW3S2R90	90±30%	600	4.0	2.0	100	50	1.0
KW3S2R140	140±30%	600	4.0	2.0	100	100	1.0
KW3S2R200	200±20%	600	4.0	2.0	100	100	1.0
KW3S2R350	350±20%	800	4.0	2.0	100	100	1.0
KW3S2R470	470±20%	900	4.0	2.0	100	100	1.0
KW3S2R600	600±20%	1000	4.0	2.0	100	100	1.0

Solderability test

Solderability	
Solder Pot Temperature:	245±5°C
Solder Dwell Time:	4-6 seconds

Product Characteristics

Lead Material	Copper or iron nickel alloy
Body Material	Ceramics
Terminal Finish	100% Matte-Tin Plated
Weight	0.180g

Temperature Range

Operating temp range : -55°C to +125°C

Storage temp range : -40°C to +85°C

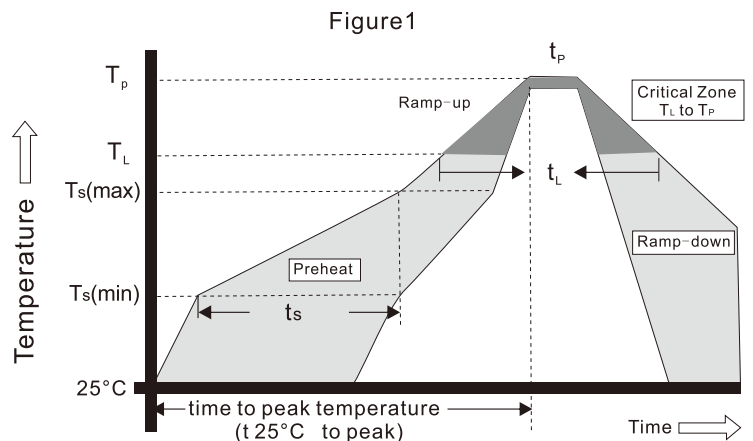
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Environmental Reliability Characteristics

Testing items	Technical standards
High Temperature Storage Test	Temperature:85°C Time:2H
Low Temperature Storage Test	Temperature:-40°C Time:2H
Vibration	Frequency:100-500Hz Amplitude:0.15mm Time:45mins
Resistance of soldering heat	Temperature:260±5°C Time of dip soldering: 10s, 1 time

Soldering Parameters - Reflow Soldering (Surface Mount Devices)

Reflow Condition		Pb – Free assembly
Heat Pre	Temperature Min	150°C
	Temperature Max	200°C
	Time (Min to Max)	60 – 180 secs
Average ramp up rate (Liquidus Temp (TL) to peak)		3°C/second max
Ts(max) to TL - Ramp-up Rate		5°C/second max
Reflow	- Temperature (TL) (Liquidus)	217°C
	- Temperature (tL)	60 – 150 seconds
Peak Temperature (Tp)		260+0/-5 °C
Time within 5°C of actual peak Temperature (tp)		8 – 20 seconds
Ramp-down Rate		6°C/second max
Time 25°C to peak Temperature (Tp)		8 minutes Max.
Do not exceed		260°C



Packaging

Part Number	Description	Quantity
KW3S2R	2000PCS Per Reel, 8000PCS in box, 40000PCS Outer box	40000PCS